

In the claims:

Please cancel claims 1-18.

Please add new claims 19-35 as follows:

19. (New) A positioning apparatus for transferring at least one electronic component from a first flat support a second flat support, the apparatus comprising

a camera device for detecting a first location of one of the electronic components on the first flat support and a second location on the second flat support for receiving; and

an ejection device for removing the one electronic component based on the detected first location and for applying the one electronic component to the second support flat support based on the detected second location,

wherein the first support is supported on a first support plane, and

wherein the second flat support extends parallel to the first support on a second support plane.

20. (New) The apparatus according to claim 19, further comprising:

a first positioning device for positioning the first support relative to an axis; and

a second positioning device for positioning the second support relative to the axis.

21. (New) The apparatus according to claim 20, wherein at least one of the first and second positioning devices performs rotation of at least one of the first and second supports about a rotation axis perpendicular to the support planes.

22. (New) The apparatus according to claim 21, further comprising:

a third positioning device connected the ejection device for positioning the ejection device parallel to the support planes.

23. (New) The apparatus according to claim 19, wherein the first flat support includes on or more wafers and the second support includes a strip-shaped substrate.

24. (New) The apparatus according to claim 23, wherein the strip-shaped substrate includes an optically transparent material.

25. (New) The apparatus according to claim 23, wherein the strip-shaped substrate includes a partially perforated material.

26. (New) The apparatus according to claim 23, wherein the second support includes components which were applied to the strip-shaped substrate prior to the transfer of the electronic component.

27. (New) The apparatus according to claim 26, wherein the second support includes bond contacts for bonding the electronic component at the predetermined location on the strip-shaped substrate.

28. (New) The apparatus according to claim 19, wherein the second support comprises individual substrate elements, which are spaced apart from one another.

29. (New) The apparatus according to claim 19, wherein the camera device is arranged below the second support, the camera device and the ejection device are arranged with respect to a vertical axis.

30. (New) The apparatus according to claim 29, further comprising a flat support element arranged between the camera device and the second support for supporting a portion of the second support that is made of an optically transparent material.

31. (New) The apparatus according to claim 30, wherein the support element is displaceable along the vertical axis and is heated.

32. (New) The apparatus according to claim 19, wherein the camera device comprises an evaluation device for evaluating and comparing the detected position data.

33. (New) The apparatus according to claim 32, further comprising a control device for controlling the positioning devices based on a comparison of position data.

34. (New) A positioning method for transferring at least one electronic component from a first flat support in a first support plane to at least one predetermined location on a second flat support, which extends parallel to the first support, comprising:

optically detecting position of a first one of the electronic components arranged on the first support using a camera device arranged below the second support, the second flat support being displaced along a second support plane below the first flat support and including an optically transparent material some regions;

positioning one of the predetermined locations of the second support above the camera device;

detecting the positioned predetermined location using the camera device; and

aligning the first support with the second support using a positioning device by at least one of displacement or rotation thereof with respect to one another within the support planes, such that the camera device, the detected predetermined location on the second support, the first electronic component arranged on the first support and an ejection device lie on an imaginary common straight line.

35. (New) The method according to claim 34, wherein the second support is designed as a strip-shaped substrate is moved in the second support plane at a displacement speed which is calculated from the distance between the electronic components to be removed successively from the first support, a displacement speed of the first support and position data of an optically

transparent region of the second support, through which the camera device detects position data during displacement of the second support.

